

**INTEGRATED CIRCUIT HEATING SYSTEM AND METHOD THEREFOR**

**Related Patent Documents**

on  
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This application is related to and fully incorporates U.S. Patent Application  
5 Serial No. 09/585921 (AMDA.478PA), entitled "Internal Heating System and  
Method Therefor," and filed concurrently herewith.

**Field of the Invention**

10 The present invention relates generally to semiconductor analysis and, more  
particularly, to semiconductor analysis involving temperature control of a  
semiconductor die.

**Background of the Invention**

15 The electronics industry continues to rely upon advances in semiconductor  
technology, including integrated circuits (ICs), to realize higher-functioning devices in  
more compact areas. For many applications, realizing higher-functioning devices  
requires integrating a large number of electronic devices into a single silicon die. In  
addition, many of the individual devices within the die are being manufactured with  
smaller physical dimensions. As the number of electronic devices per given area of the  
20 silicon die increases, and as the size of the individual devices decreases, testing  
processes become more important and more difficult.

Many integrated circuit dice include circuits having random defects. These  
defects can recover or fail under particular operating conditions and at higher